Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	**: Required Field*	

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-10-17
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	Material Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by
Antonella Lanzafame
Date: 2024.10.17
11:46:00 CEST

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Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
VNH9030AQTR	B0DY*VH93ABC	A	CA2A	2024-10-17
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	150	mg	Each	ECOPACK® 3
Identity	**Authority**			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
3	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape	
QFN	6 x 6	26	flat	
Comment				
Comment	B0DY QFN 6X6 TRIPLE PAD L26+2			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false

Exemption Id.	**Description**

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	**Response**
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false

Exemption Id.	**Description**

QueryList : California Prop65 list, dated 17th Nov 2023			**Response**
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	**amount in product (mg)**	**Application**	**ppm in product**
Nickel	0.035	alloy	233

QueryList :Customer	**Response**
QUERY	**Response**

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				**Response**
QUERY				**Response**
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hazardous substance				
Lead (Pb)	**Cadmium (Cd)**	**Mercury (Hg)**	**Hexavalent Chromium (Cr VI)**	**PBB & PBDE**
O	O	O	O	O

QueryList : REACH-27th June 2024				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material

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QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	**Tin, Tungsten,**

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True

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Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**B0DY*VH93ABC**		150.0000		7000003.0	999999.0
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Dies	M-011 Other inorganic materials	2.909	mg	supplier	die	Silicon(Si)	7440-21-3		2.343	mg	805431	15620
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.099	mg	34032	660
				supplier	metallisation	Copper(Cu)	7440-50-8		0.041	mg	14094	273
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.035	mg	12032	233
				supplier	metallisation	Silver(Ag)	7440-22-4		0.014	mg	4813	93
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.013	mg	4469	87
				supplier	metallisation	Tungsten(W)	7440-33-7		0.176	mg	60502	1173
				supplier	metallisation	Vanadium(V)	7440-62-2		0.003	mg	1031	20
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.017	mg	5844	113
				supplier	passivation	Silicon oxide	7631-86-9		0.095	mg	32657	633
				supplier	polymer coating	polyimide	proprietary		0.073	mg	25095	487
Leadframe	M-004 Copper and its alloys	42.577	mg	supplier	alloy	Copper(Cu)	7440-50-8		40.212	mg	944454	268080
				supplier	alloy	Iron (Fe)	7439-89-6		0.708	mg	16629	4720
				supplier	alloy	Iron phosphide	26508-33-8		0.165	mg	3875	1100
				supplier	alloy	Zinc(Zn)	7440-66-6		0.053	mg	1245	353
				supplier	metallization	Silver (Ag)	7440-22-4		1.439	mg	33798	9593
Die attach	M-011 Other inorganic materials	0.345	mg	supplier	glue	Silver(Ag)	7440-22-4		0.297	mg	860870	1980
				supplier	glue	phenolic Resin	9003-35-4		0.016	mg	46377	107
				supplier	glue	Hexanediol diglycidyl ether	16096-31-4		0.016	mg	46377	107
				supplier	glue	Bisphenol F type epoxy resin	9003-36-5		0.002	mg	5797	13
				supplier	glue	Epoxy Cresol Novolak	29690-82-2		0.012	mg	34783	80
				supplier	glue	Epoxyde bisphenol A resin	25068-38-6		0.002	mg	5797	13
Bonding wires	M-004 Copper and its alloys	1.565	mg	supplier	wire	Copper(Cu)	7440-50-8		1.565	mg	1000000	10433
Bonding wires 2	M-004 Copper and its alloys	0.118	mg	supplier	wire	Copper(Cu)	7440-50-8		0.118	mg	1000000	787
Encapsulation	M-011 Other inorganic materials	101.421	mg	supplier	mold compound	Silica vitreous	60676-86-0		89.251	mg	880005	595007
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		5.071	mg	50000	33807
				supplier	mold compound	Phenolic resin	205830-20-2		3.955	mg	38996	26367
				supplier	mold compound	Epoxy type resin	proprietary		2.028	mg	19996	13520
				supplier	mold compound	Carbon black	1333-86-4		0.203	mg	2002	1353
				supplier	mold compound	other	proprietary		0.913	mg	9002	6087
Connections coating	Solder	1.065	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		1.065	mg	1000000	7100

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